

ABSTRACT

MODULAR MOLDING ASSEMBLY FOR ELECTRONIC DEVICES

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A modular molding assembly comprises an input module for loading electronic devices for molding, a press station including one or more molding presses for molding the electronic devices, an output module for offloading molded electronic devices after they have been molded and a carrier that is movable at least
10 between the input module and the press station and/or the press station and the output module. The carrier has an adaptor located thereon for detachably mounting a first attachment or a second attachment which is operative to perform a function of transporting the electronic devices and/or introducing a molding compound to the press station for conducting molding. The first and second
15 attachments each has a corresponding mounting device for detachably mounting the first or second attachment onto the adapter and the first attachment has a different function from the second attachment.

(FIG. 1)